DEFENSE LOGISTICS AGENCY
LAND AND MARITIME
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

Mr. Harrison Betz
Quality Engineering
Analog Devices, Inc.
4200 NW Pacific Rim Blvd
Camas, WA 98607

June 3, 2024

Dear Mr. Betz

Re: Full Certification Class Q and V for MIL-PRF-38535; FSC 5962; VQ(VQC-24-038774); CN: 087845

Analog Devices, Inc. (ADI) has demonstrated to the DLA Land and Maritime that it complies with MIL-PRF-38535, the performance specification used by the Department of Defense for monolithic integrated circuits that operate in severe environments.

This letter supersedes previous Level Q and V Certification letters granted to ADI, effective immediately, to reflect the current certification status of your facilities as documented on the enclosed attachment.

In addition, the parts that are manufactured using the certified technology flows are being listed on the QML-38535. This will allow ADI to mark parts with "Q" or "QML". These designators have been authorized by the Department of Defense for parts that have been produced to a QML specification, (i.e., one which allows less government oversight), the use of world-wide commercial production lines, reduced finished product testing based on statistical process controls (SPC), and other cost advantages.

Testing must be performed using the facilities and methods listed in the Laboratory Suitability letter DLA Land and Maritime-VQC-24-038775, or at facilities approved by the ADI Technical Review Board using its MIL-PRF-38535 Quality Management Program Plan.

This certification is subject to the conditions in DoD 4120.24-M, Defense Standardization Program and SD-6.

Any and all of the facilities mentioned on the enclosure are subject to an audit by the Qualifying Activity at any time. Offshore facilities are subject to all of the conditions of MIL-PRF-38535.

QPL/QML manufacturers shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products. Failure to provide prior notification may be grounds for removal from QML-38535.

Finally, it is requested that the following activities be reported promptly to DLA Land and Maritime:

1. Changes to certified facilities, process flows, or approved testing subcontractors
2. Problem evaluation and a corrective action when:
   a. A Technology Conformance Inspection (TCI) failure has been validated
   b. The reliability of shipped parts is questionable.
3. Test optimization, including:
   a. Implementation - paragraph J.3.12, Appendix J, MIL-PRF-38535
   b. Changing, suspending or canceling a prior test optimization
4. Additions or deletions of parts in the QML-38535
5. Change of company QML contact or other key QML personnel

This certification is valid until terminated by written notice from the qualifying activity. If warranted, it may be withdrawn by this Agency at any time.

If you have any questions, please contact Mr. Scott Thomas at 614-692-0587.

Sincerely,

HEBER.ROBERT.M.1230099495 Digitally signed by HEBER.ROBERT.M.1230099495 Date: 2024.06.03 11:41:39 -04'00'

ROBERT HEBER
Chief
Sourcing and Qualification Division

Enclosures

Enclosure (1) to DLA Land and Maritime-VQ (VQC-24-038774)

OPERATION	LOCATION	TECHNOLOGY
Wafer Fab	Wilmington, MA Class Q & V	Bipolar, BiFET, Bi-CMOS per ADI-0088
	Limerick, Ireland Class Q & V	CMOS, Bi-MOS per ADI-0088
	Camas, WA Class Q, V	Bipolar, CMOS, BiCMOS
	TSMC Hsin-Chu, Taiwan (Class Q)	CMOS, Bi-MOS per ADI-0088
	Global Foundries Singapore (Class Q)	CMOS, Bi-MOS per ADI-0088
Backmetal	Plot 21(B) Phase 4 Bayan Lapas Free Trade Zone 11900 Penang, Malaysia	Bipolar, CMOS, BiCMOS
Assembly & Test	ADI, Philippines Class Q & V	Ceramic, TO Can
	Team Pacific Taguig, Manila, Philippines	TO Can
Test	**VPT Rad** Chelmsford, MA	Radiation Electrical Test per MIL-STD- 883 TM1019 and GS09230
	TSSI/ Team Quest	Burn-in and Life Test
Test/Screen/TCI	See DLA Land and Maritime-VQC-24-038775	Laboratory Suitability letter

Enclosure (3) to DLA Land and Maritime-VQ (VQC-24-038774) - Package Information

Type	LEAD RANGE	LEAD FINISH	LEAD PITCH
DIP	8-48	solder/gold	100-600 mil
Flatpack	2-52	solder, gold	25 mil
JLCC	44	solder, gold	
Leadless Chip Carrier	20-44	solder/gold	50 mil
Metal Can	2-12	solder/gold	100-400 mil